



Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I ² C, IrDA, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	50
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32lg942f128g-e-qfp64

1. Feature List

- ARM Cortex-M3 CPU platform
 - High Performance 32-bit processor @ up to 48 MHz
 - Memory Protection Unit
 - Wake-up Interrupt Controller
 - SysTick System Timer
- Flexible Energy Management System
 - 20 nA @ 3 V Shutoff Mode
 - 0.4 μ A @ 3 V Shutoff Mode with RTC
 - 0.65 μ A @ 3 V Stop Mode, including Power-on Reset, Brown-out Detector, RAM and CPU retention
 - 0.95 μ A @ 3 V Deep Sleep Mode, including RTC with 32.768 kHz oscillator, Power-on Reset, Brown-out Detector, RAM and CPU retention
 - 63 μ A/MHz @ 3 V Sleep Mode
 - 211 μ A/MHz @ 3 V Run Mode, with code executed from flash
- 256/128/64 kB Flash
- 32 kB RAM
- Up to 93 General Purpose I/O pins
 - Configurable push-pull, open-drain, pull-up/down, input filter, drive strength
 - Configurable peripheral I/O locations
 - 16 asynchronous external interrupts
 - Output state retention and wake-up from Shutoff Mode
- 12 Channel DMA Controller
- 12 Channel Peripheral Reflex System (PRS) for autonomous inter-peripheral signaling
- Hardware AES with 128/256-bit keys in 54/75 cycles
- Timers/Counters
 - 4 $\times$ 16-bit Timer/Counter
 - 4 $\times$ 3 Compare/Capture/PWM channels
 - Dead-Time Insertion on TIMER0
 - 16-bit Low Energy Timer
 - 1 $\times$ 24-bit Real-Time Counter and 1 $\times$ 32-bit Real-Time Counter
 - 3 $\times$ 16/8-bit Pulse Counter
 - Watchdog Timer with dedicated RC oscillator @ 50 nA
- Integrated LCD Controller for up to 8 $\times$ 36 segments
 - Voltage boost, adjustable contrast and autonomous animation
- Backup Power Domain
 - RTC and retention registers in a separate power domain, available in all energy modes
 - Operation from backup battery when main power drains out
- External Bus Interface for up to 4 $\times$ 256 MB of external memory mapped space
 - TFT Controller with Direct Drive
- Communication interfaces
 - Up to 3 $\times$ Universal Synchronous/Asynchronous Receiver/Transmitter
 - UART/SPI/SmartCard (ISO 7816)/IrDA/I2S
 - 2 $\times$ Universal Asynchronous Receiver/Transmitter
 - 2 $\times$ Low Energy UART
 - Autonomous operation with DMA in Deep Sleep Mode
 - 2 $\times$ I²C Interface with SMBus support
 - Address recognition in Stop Mode
 - Universal Serial Bus (USB) with Host & OTG support
 - Fully USB 2.0 compliant
 - On-chip PHY and embedded 5V to 3.3V regulator
- Ultra low power precision analog peripherals
 - 12-bit 1 Msamples/s Analog to Digital Converter

- 8 single ended channels/4 differential channels
- On-chip temperature sensor
- 12-bit 500 ksamples/s Digital to Analog Converter
 - 2 single ended channels/1 differential channel
- Up to 2× Analog Comparator
 - Capacitive sensing with up to 16 inputs
- 3× Operational Amplifier
 - 6.1 MHz GBW, Rail-to-rail, Programmable Gain
- Supply Voltage Comparator
- Low Energy Sensor Interface (LESENSE)
 - Autonomous sensor monitoring in Deep Sleep Mode
 - Wide range of sensors supported, including LC sensors and capacitive buttons
- Ultra efficient Power-on Reset and Brown-Out Detector
- Debug Interface
 - 2-pin Serial Wire Debug interface
 - 1-pin Serial Wire Viewer
 - Embedded Trace Module v3.5 (ETM)
- Pre-Programmed USB/UART Bootloader
- Temperature range -40 to 85 °C
- Single power supply 1.98 to 3.8 V
- Packages:
 - BGA112
 - BGA120
 - CSP81
 - LQFP100
 - TQFP64
 - QFN64
 - Full wafer

3.2.2 EFM32LG232

The features of the EFM32LG232 is a subset of the feature set described in the EFM32LG Reference Manual. The following table describes device specific implementation of the features.

Table 3.2. EFM32LG232 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
I2C1	Full configuration	I2C1_SDA, I2C1_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	Full configuration with I2S	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	Full configuration with I2S	US2_TX, US2_RX, US2_CLK, US2_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
LEUART1	Full configuration	LEU1_TX, LEU1_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
TIMER3	Full configuration	TIM3_CC[2:0]
RTC	Full configuration	NA
BURTC	Full configuration	NA
LETIMER0	Full configuration	LET0_O[1:0]
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
PCNT1	Full configuration, 8-bit count register	PCNT1_S[1:0]
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx

Module	Configuration	Pin Connections
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	85 pins	Available pins are shown in 5.3.3 GPIO Pinout Overview

Module	Configuration	Pin Connections
AES	Full configuration	NA
GPIO	53 pins	Available pins are shown in 5.13.3 GPIO Pinout Overview
LCD	Full configuration	LCD_SEG[17:0], LCD_COM[7:0], LCD_BCAP_P, LCD_BCAP_N, LCD_BEXT

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Gain Bandwidth Product	GBW _{OPAMP}	(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, DC bias = 0.3 V	—	0.393 ¹	—	MHz
		(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, DC bias = 1 V	—	0.487 ¹	—	MHz
		(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, DC bias = 2 V	—	0.392 ¹	—	MHz
		(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, DC bias = 2.7 V	—	0.318 ¹	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, DC bias = 0.3 V	—	1.595 ¹	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, DC bias = 1 V	—	2.661 ¹	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, DC bias = 2 V	—	2.566 ¹	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, DC bias = 2.7 V	—	1.787 ¹	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, DC bias = 0.3 V	—	0.460 ¹	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, DC bias = 1 V	—	0.447 ¹	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, DC bias = 2 V	—	0.372 ¹	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, DC bias = 2.7 V	—	0.295 ¹	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, DC bias = 0.3 V	—	1.890 ¹	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, DC bias = 1 V	—	2.849 ¹	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, DC bias = 2 V	—	2.561 ¹	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, DC bias = 2.7 V	—	1.705 ¹	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, DC bias = 0.3 V	—	0.339 ¹	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, DC bias = 1 V	—	0.432 ¹	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, DC bias = 2 V	—	0.347 ¹	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, DC bias = 2.7 V	—	0.286 ¹	—	MHz
		(OPA2)BIASPROG=0x4,(OPA2)HALF-BIAS=0x1, DC bias = 0.3 V	—	1.271 ¹	—	MHz
		(OPA2)BIASPROG=0x4,(OPA2)HALF-BIAS=0x1, DC bias = 1 V	—	1.429 ¹	—	MHz
		(OPA2)BIASPROG=0x4,(OPA2)HALF-BIAS=0x1, DC bias = 2 V	—	1.283 ¹	—	MHz

5.2.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.5. Alternate functionality overview

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5							Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6							Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7							Analog comparator ACMP0, channel 7.
ACMP0_O	PE13		PD6					Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8							Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9							Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10							Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11							Analog comparator ACMP1, channel 3.
ACMP1_CH4	PC12							Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13							Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14							Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15							Analog comparator ACMP1, channel 7.
ACMP1_O	PF2		PD7					Analog comparator ACMP1, digital output.
ADC0_CH0	PD0							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1							Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2							Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3							Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
TIM2_CC2	PA10		PC10					Timer 2 Capture Compare input / output channel 2.
TIM3_CC0	PE14							Timer 3 Capture Compare input / output channel 0.
TIM3_CC1	PE15							Timer 3 Capture Compare input / output channel 1.
TIM3_CC2	PA15	PE2						Timer 3 Capture Compare input / output channel 2.
U0_RX			PA4	PC15				UART0 Receive input.
U0_TX			PA3	PC14				UART0 Transmit output. Also used as receive input in half duplex communication.
U1_RX	PC13	PF11		PE3				UART1 Receive input.
U1_TX	PC12	PF10		PE2				UART1 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9	PC15	PB13	PB13		USART0 clock input / output.
US0_CS	PE13	PE4	PC8	PC14	PB14	PB14		USART0 chip select input / output.
US0_RX	PE11		PC10	PE12	PB8	PC1		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10		PC11	PE13	PB7	PC0		USART0 Asynchronous Transmit. Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2	PF0					USART1 clock input / output.
US1_CS	PB8	PD3	PF1					USART1 chip select input / output.
US1_RX	PC1	PD1	PD6					USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0	PD7					USART1 Asynchronous Transmit. Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5						USART2 clock input / output.
US2_CS	PC5	PB6						USART2 chip select input / output.
US2_RX	PC3	PB4						USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3						USART2 Asynchronous Transmit. Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PF10							USB D- pin.
USB_DMPU	PD2							USB D- Pullup control.
USB_DP	PF11							USB D+ pin.

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
26	PA7		EBI_CSTFT #0/1/2			
27	PA8		EBI_DCLK #0/1/2	TIM2_CC0 #0		
28	PA9		EBI_DTEN #0/1/2	TIM2_CC1 #0		
29	PA10		EBI_VSNC #0/1/2	TIM2_CC2 #0		
30	PA11		EBI_HSNC #0/1/2			
31	IOVDD_2	Digital IO power supply 2.				
32	VSS	Ground.				
33	PA12		EBI_A00 #0/1/2	TIM2_CC0 #1		
34	PA13		EBI_A01 #0/1/2	TIM2_CC1 #1		
35	PA14		EBI_A02 #0/1/2	TIM2_CC2 #1		
36	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
37	PB9		EBI_A03 #0/1/2		U1_TX #2	
38	PB10		EBI_A04 #0/1/2		U1_RX #2	
39	PB11	DAC0_OUT0 / OPAMP_OUT0		TIM1_CC2 #3 LE- TIM0_OUT0 #1	I2C1_SDA #1	
40	PB12	DAC0_OUT1 / OPAMP_OUT1		LETIM0_OUT1 #1	I2C1_SCL #1	
41	AVDD_1	Analog power supply 1.				
42	PB13	HFX TAL_P			US0_CLK #4/5 LEU0_TX #1	
43	PB14	HFX TAL_N			US0_CS #4/5 LEU0_RX #1	
44	IOVDD_3	Digital IO power supply 3.				
45	AVDD_0	Analog power supply 0.				
46	PD0	ADC0_CH0 DAC0_OUT0ALT #4/ OPAMP_OUT0ALT OPAMP_OUT2 #1		PCNT2_S0IN #0	US1_TX #1	
47	PD1	ADC0_CH1 DAC0_OUT1ALT #4/ OPAMP_OUT1ALT		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	DBG_SWO #2
48	PD2	ADC0_CH2	EBI_A27 #0/1/2	TIM0_CC1 #3	USB_DMPU #0 US1_CLK #1	DBG_SWO #3
49	PD3	ADC0_CH3 OPAMP_N2		TIM0_CC2 #3	US1_CS #1	ETM_TD1 #0/2
50	PD4	ADC0_CH4 OPAMP_P2			LEU0_TX #0	ETM_TD2 #0/2
51	PD5	ADC0_CH5 OPAMP_OUT2 #0			LEU0_RX #0	ETM_TD3 #0/2

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_AD10	PA1	PA1	PA1					External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2	PA2	PA2					External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3	PA3	PA3					External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	PA4	PA4	PA4					External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5	PA5	PA5					External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6	PA6	PA6					External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE		PC11	PC11					External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	PF2	PF2	PF2					External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	PF6	PF6	PF6					External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	PF7	PF7	PF7					External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	PD9	PD9	PD9					External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10	PD10	PD10					External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11	PD11	PD11					External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12	PD12	PD12					External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	PA7	PA7	PA7					External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	PA8	PA8	PA8					External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	PA9	PA9	PA9					External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNCR	PA11	PA11	PA11					External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREN	PC3	PC3	PC3					External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEN	PC5	PC5	PC5					External Bus Interface (EBI) NAND Write Enable output.
EBI_REN	PF5	PF9	PF5					External Bus Interface (EBI) Read Enable output.
EBI_VSNCR	PA10	PA10	PA10					External Bus Interface (EBI) TFT Vertical Synchronization pin.
EBI_WEN		PF8						External Bus Interface (EBI) Write Enable output.
ETM_TCLK	PD7	PF8	PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6	PF9	PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3	PD13	PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4	PB15	PD4	PA4				Embedded Trace Module ETM data 2.

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
USB_VREGI	USB_V REGI							USB Input to internal 3.3 V regulator
USB_VREGO	USB_V REGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

5.10.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32LG390 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.30. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	PA15	PA14	PA13	PA12	PA11	PA10	PA9	PA8	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
Port B	PB15	PB14	PB13	PB12	PB11	PB10	PB9	PB8	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
Port C	—	—	—	—	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Port D	PD15	PD14	PD13	PD12	PD11	PD10	PD9	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	PE7	PE6	PE5	PE4	PE3	PE2	PE1	PE0
Port F	—	—	—	PF12	PF11	PF10	PF9	PF8	PF7	PF6	PF5	—	—	PF2	PF1	PF0

5.10.4 Opamp Pinout Overview

The specific opamp terminals available in EFM32LG390 is shown in the following figure.

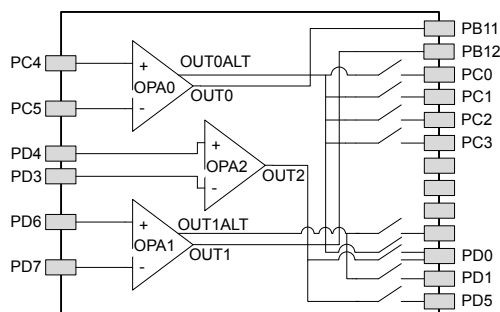


Figure 5.20. Opamp Pinout

5.12 EFM32LG840 (QFN64)

5.12.1 Pinout

The EFM32LG840 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

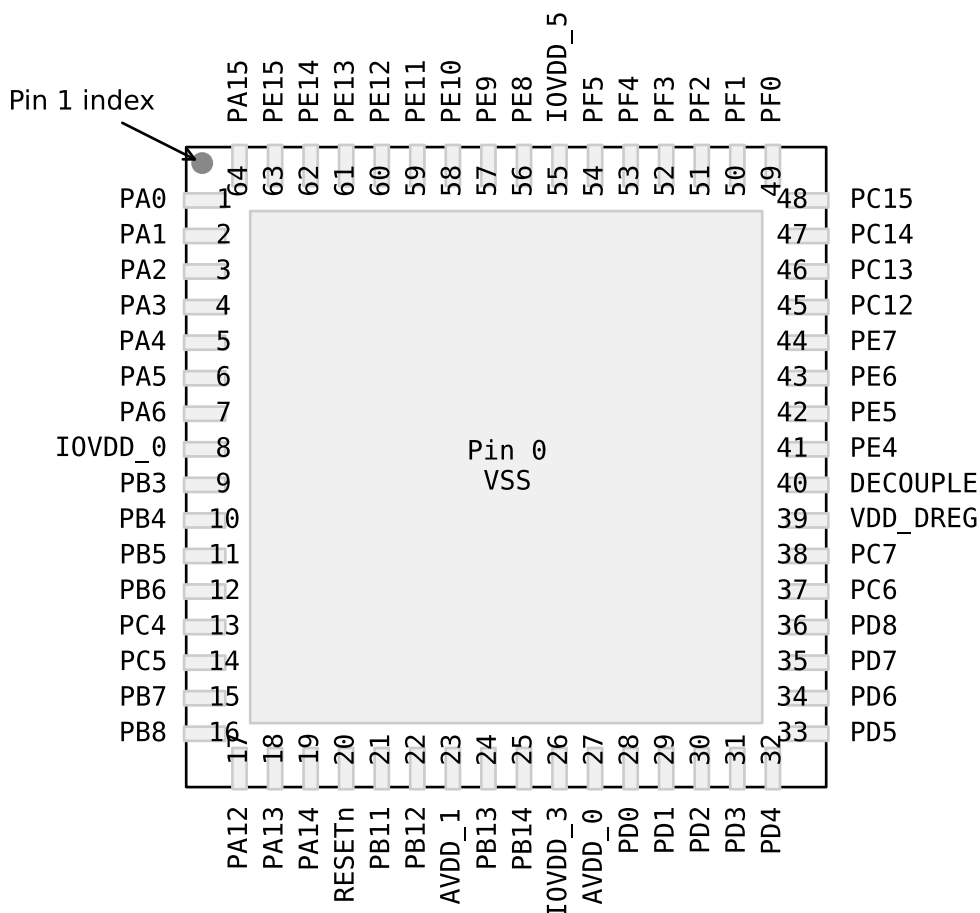


Figure 5.23. EFM32LG840 Pinout (top view, not to scale)

Table 5.34. Device Pinout

QFN64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	VSS	Ground.			
1	PA0	LCD_SEG13	TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU0

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LCD_SEG14	PA1							LCD segment line 14. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG15	PA2							LCD segment line 15. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG16	PA3							LCD segment line 16. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG17	PA4							LCD segment line 17. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG18	PA5							LCD segment line 18. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG20/ LCD_COM4	PB3							LCD segment line 20. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 4
LCD_SEG21/ LCD_COM5	PB4							LCD segment line 21. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 5
LCD_SEG22/ LCD_COM6	PB5							LCD segment line 22. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 6
LCD_SEG23/ LCD_COM7	PB6							LCD segment line 23. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 7
LES_ALTEX0	PD6							LESENSE alternate exite output 0.
LES_ALTEX1	PD7							LESENSE alternate exite output 1.
LES_ALTEX2	PA3							LESENSE alternate exite output 2.
LES_ALTEX3	PA4							LESENSE alternate exite output 3.
LES_ALTEX4	PA5							LESENSE alternate exite output 4.
LES_ALTEX5	PE11							LESENSE alternate exite output 5.
LES_ALTEX6	PE12							LESENSE alternate exite output 6.
LES_ALTEX7	PE13							LESENSE alternate exite output 7.
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LES_CH12	PC12							LESENSE channel 12.
LES_CH13	PC13							LESENSE channel 13.
LES_CH14	PC14							LESENSE channel 14.
LES_CH15	PC15							LESENSE channel 15.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7		PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.
BU_STAT	PE3							Backup Power Domain status, whether or not the system is in backup mode
BU_VIN	PD8							Battery input for Backup Power Domain
BU_VOUT	PE2							Power output for Backup Power Domain
CMU_CLK0	PA2	PC12	PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 /OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							Digital to Analog Converter DAC0_OUT1 / OPAMP output channel number 1.
DAC0_OUT1ALT / OPAMP_OUT1ALT	PC12	PC13	PC14	PC15	PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2	PC15	PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_A00	PA12	PA12	PA12					External Bus Interface (EBI) address output pin 00.
EBI_A01	PA13	PA13	PA13					External Bus Interface (EBI) address output pin 01.
EBI_A02	PA14	PA14	PA14					External Bus Interface (EBI) address output pin 02.
EBI_A03	PB9	PB9	PB9					External Bus Interface (EBI) address output pin 03.
EBI_A04	PB10	PB10	PB10					External Bus Interface (EBI) address output pin 04.
EBI_A05	PC6	PC6	PC6					External Bus Interface (EBI) address output pin 05.

5.17 EFM32LG900 (Wafer)

5.17.1 Padout

The EFM32LG900 padout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pad are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

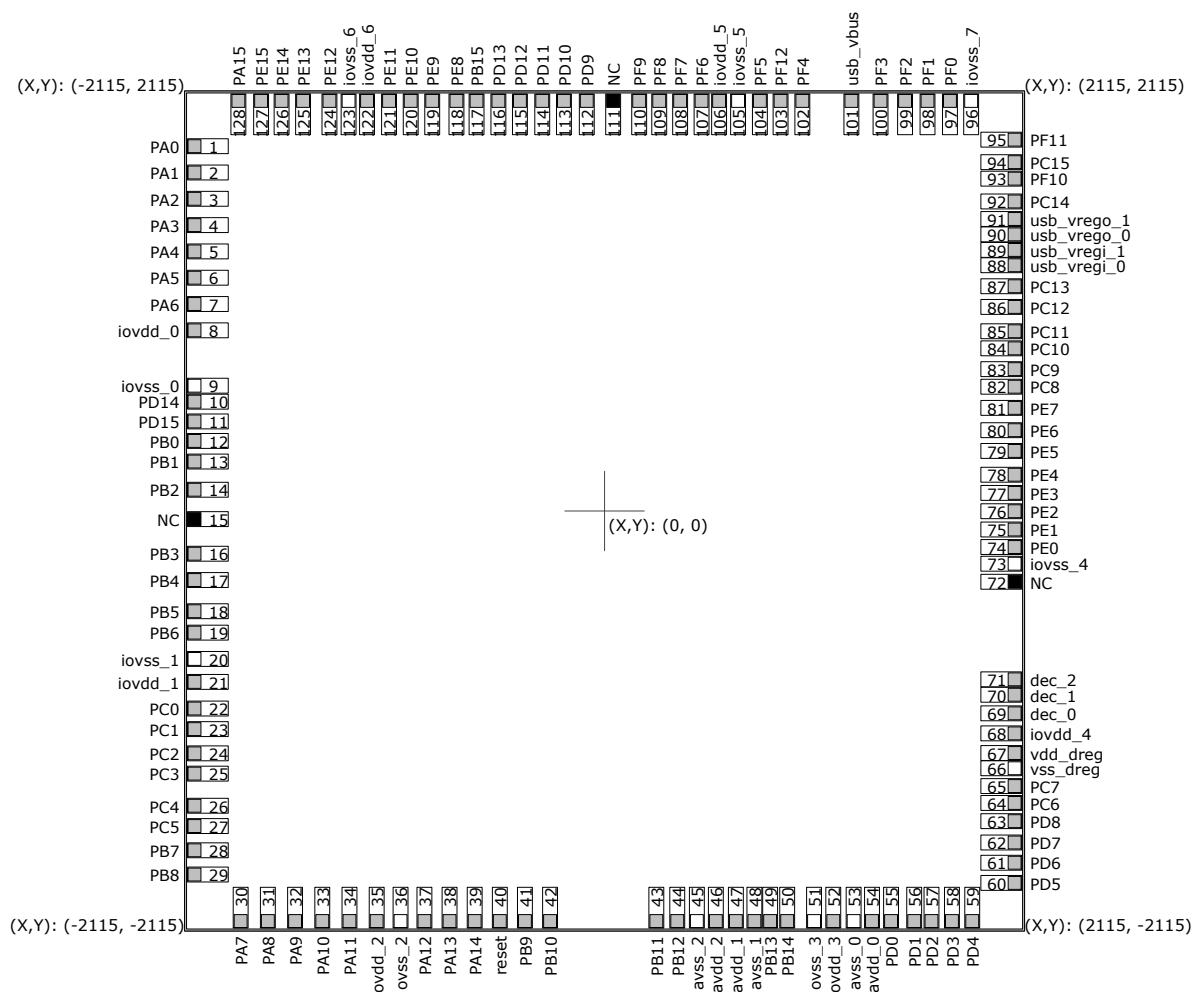


Figure 5.33. EFM32LG900 Padout (top view, not to scale)

The pad coordinates represent the center of the pad opening relative to the die center.

Table 5.49. Device Padout

Water Pads and Coordinates				Pad Alternative Functionality / Description				
Pad #	Pad Name	X (μm)	Y (μm)	Analog	EBI	Timers	Communica- tion	Other
1	PA0	-2065.0	1837.0	LCD_SEG13	EBI_AD09 #0/1/2	TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU 0
2	PA1	-2065.0	1704.6	LCD_SEG14	EBI_AD10 #0/1/2	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
3	PA2	-2065.0	1572.1	LCD_SEG15	EBI_AD11 #0/1/2	TIM0_CC2 #0/1		CMU_CLK0 #0 ETM_TDO #3

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.
BU_STAT	PE3							Backup Power Domain status, whether or not the system is in backup mode
BU_VIN	PD8							Battery input for Backup Power Domain
BU_VOUT	PE2							Power output for Backup Power Domain
CMU_CLK0	PA2	PC12	PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 / OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							Digital to Analog Converter DAC0_OUT1 / OPAMP output channel number 1.
DAC0_OUT1ALT / OPAMP_OUT1ALT	PC12	PC13	PC14	PC15	PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2	PC15	PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_A00	PA12	PA12	PA12					External Bus Interface (EBI) address output pin 00.
EBI_A01	PA13	PA13	PA13					External Bus Interface (EBI) address output pin 01.
EBI_A02	PA14	PA14	PA14					External Bus Interface (EBI) address output pin 02.
EBI_A03	PB9	PB9	PB9					External Bus Interface (EBI) address output pin 03.
EBI_A04	PB10	PB10	PB10					External Bus Interface (EBI) address output pin 04.
EBI_A05	PC6	PC6	PC6					External Bus Interface (EBI) address output pin 05.

5.20.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.59. Alternate functionality overview

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5							Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6							Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7							Analog comparator ACMP0, channel 7.
ACMP0_O	PE13	PE2	PD6					Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8							Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9							Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10							Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11							Analog comparator ACMP1, channel 3.
ACMP1_O	PF2	PE3	PD7					Analog comparator ACMP1, digital output.
ADC0_CH0	PD0							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1							Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2							Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3							Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LCD_SEG7	PE11							LCD segment line 7. Segments 4, 5, 6 and 7 are controlled by SEGEN1.
LCD_SEG8	PE12							LCD segment line 8. Segments 8, 9, 10 and 11 are controlled by SEGEN2.
LCD_SEG9	PE13							LCD segment line 9. Segments 8, 9, 10 and 11 are controlled by SEGEN2.
LCD_SEG10	PE14							LCD segment line 10. Segments 8, 9, 10 and 11 are controlled by SEGEN2.
LCD_SEG11	PE15							LCD segment line 11. Segments 8, 9, 10 and 11 are controlled by SEGEN2.
LCD_SEG12	PA15							LCD segment line 12. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG13	PA0							LCD segment line 13. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG14	PA1							LCD segment line 14. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG15	PA2							LCD segment line 15. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG16	PA3							LCD segment line 16. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG17	PA4							LCD segment line 17. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG18	PA5							LCD segment line 18. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG19	PA6							LCD segment line 19. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG20/ LCD_COM4	PB3							LCD segment line 20. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 4
LCD_SEG21/ LCD_COM5	PB4							LCD segment line 21. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 5
LCD_SEG22/ LCD_COM6	PB5							LCD segment line 22. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 6
LCD_SEG23/ LCD_COM7	PB6							LCD segment line 23. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 7
LCD_SEG24	PF6							LCD segment line 24. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG25	PF7							LCD segment line 25. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG26	PF8							LCD segment line 26. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG27	PF9							LCD segment line 27. Segments 24, 25, 26 and 27 are controlled by SEGEN6.

DIM	MIN	NOM	MAX	DIM	MIN	NOM	MAX
b	0.17	0.22	0.27	S	0.20	—	—
b1	0.17	0.20	0.23	θ	0°	3.5°	7°
c	0.09	—	0.20	θ1	0°	—	—
C1	0.09	—	0.16	θ2	11°	12°	13°
D	12.0 BSC			θ3	11°	12°	13°
D1	10.0 BSC						
e	0.50 BSC						
E	12.0 BSC						
E1	10.0 BSC						
L	0.45	0.60	0.75				

The TQFP64 Package is 10 by 10 mm in size and has a 0.5 mm pin pitch.

The TQFP64 Package uses Nickel-Palladium-Gold preplated leadframe.

All EFM32 packages are RoHS compliant and free of Bromine (Br) and Antimony (Sb).

For additional Quality and Environmental information, please see: <http://www.silabs.com/support/quality/pages/default.aspx>.

12. Wafer Specifications

12.1 Bonding Instructions

All pads should be bonded out, with the exception of the pads labeled “NC” and listed as “Do not connect” in Padout. Gold bond wires are recommended for these devices.

All three voltage regulator output decouple pads (DEC_0, DEC_1, DEC_2) must be bonded out and electrically connected on the PCB. In the packaged devices, these three pads are all bonded to a single DECOUPLE pin.

If the USB feature of EFM32LG900 will be used, all of the USB pads must be bonded out, and

- both USB_VREGO_0 and USB_VREGO_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB_VREGO pin.
- both USB_VREGI_0 and USB_VREGI_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB_VREGI pin.

12.2 Wafer Description

Table 12.1. Wafer and Die Information

Parameter	Value
Device Family	EFM32LG (Leopard Gecko)
Wafer Diameter	8 in
Die Dimensions (Outer edge of seal ring)	4230 μm $\times$ 4230 μm
Wafer Thickness (No backgrind)	725 μm $\pm$ 15 μm (28.54 mil $\pm$ 1 mil)
Wafer Identification	Notch
Scribe Street Width	80 μm $\times$ 160 μm
Die Per Wafer ¹	Contact sales for information
Passivation	Standard
Wafer Packaging Detail	Wafer Jar
Bond Pad Dimensions	65 μm (parallel to die edge) $\times$ 66 μm
Bond Pad Pitch Minimum	76 μm
Maximum Processing Temperature	250°C
Electronic Die Map Format	.txt
Note: 1. This is the Expected Known Good Die yielded per wafer and represents the batch order quantity (one wafer).	

12.2.1 Environmental

Bare silicon die are susceptible to mechanical damage and may be sensitive to light. When bare die must be used in an environment exposed to light, it may be necessary to cover the top and sides with an opaque material.

For additional Quality and Environmental information, please see: <http://www.silabs.com/support/quality/pages/default.aspx>.